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Applications of "<u>Embedded - Microcontrollers</u>"

-	
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f818-e-p

2.2.2.4 PIE1 Register

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

REGISTER 2-4: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1 (ADDRESS 8Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
_	ADIE	_	_	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit 7							bit 0

bit 7 Unimplemented: Read as '0' bit 6 ADIE: A/D Converter Interrupt Enable bit 1 = Enables the A/D converter interrupt 0 = Disables the A/D converter interrupt bit 5-4 Unimplemented: Read as '0' bit 3 SSPIE: Synchronous Serial Port Interrupt Enable bit 1 = Enables the SSP interrupt 0 = Disables the SSP interrupt bit 2 **CCP1IE:** CCP1 Interrupt Enable bit 1 = Enables the CCP1 interrupt 0 = Disables the CCP1 interrupt bit 1 TMR2IE: TMR2 to PR2 Match Interrupt Enable bit

1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt
bit 0

TMR1IE: TMR1 Overflow Interrupt Enable bit

1 = Enables the TMR1 overflow interrupt0 = Disables the TMR1 overflow interrupt

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

2.2.2.5 PIR1 Register

This register contains the individual flag bits for the peripheral interrupts.

Interrupt flag bits are set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-5: PIR1: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 1 (ADDRESS 0Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
_	ADIF	_	_	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit 7							hit 0

Note:

bit 7 Unimplemented: Read as '0'

bit 6 ADIF: A/D Converter Interrupt Flag bit

1 = An A/D conversion completed

0 = The A/D conversion is not complete

bit 5-4 Unimplemented: Read as '0'

bit 3 SSPIF: Synchronous Serial Port (SSP) Interrupt Flag bit

1 = The SSP interrupt condition has occurred and must be cleared in software before returning from the Interrupt Service Routine. The conditions that will set this bit are a transmission/ reception has taken place.

0 = No SSP interrupt condition has occurred

bit 2 **CCP1IF:** CCP1 Interrupt Flag bit

Capture mode:

1 = A TMR1 register capture occurred (must be cleared in software)

0 = No TMR1 register capture occurred

Compare mode:

1 = A TMR1 register compare match occurred (must be cleared in software)

0 = No TMR1 register compare match occurred

PWM mode:

Unused in this mode.

bit 1 TMR2IF: TMR2 to PR2 Match Interrupt Flag bit

1 = TMR2 to PR2 match occurred (must be cleared in software)

0 = No TMR2 to PR2 match occurred

bit 0 TMR1IF: TMR1 Overflow Interrupt Flag bit

1 = TMR1 register overflowed (must be cleared in software)

0 = TMR1 register did not overflow

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

3.0 DATA EEPROM AND FLASH PROGRAM MEMORY

The data EEPROM and Flash program memory are readable and writable during normal operation (over the full VDD range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are six SFRs used to read and write this memory:

- EECON1
- EECON2
- EEDATA
- EEDATH
- EEADR
- EEADRH

This section focuses on reading and writing data EEPROM and Flash program memory during normal operation. Refer to the appropriate device programming specification document for serial programming information.

When interfacing the data memory block, EEDATA holds the 8-bit data for read/write and EEADR holds the address of the EEPROM location being accessed. These devices have 128 or 256 bytes of data EEPROM, with an address range from 00h to 0FFh. Addresses from 80h to FFh are unimplemented on the PIC16F818 device and will read 00h. When writing to unimplemented locations, the charge pump will be turned off.

When interfacing the program memory block, the EEDATA and EEDATH registers form a two-byte word that holds the 14-bit data for read/write and the EEADR and EEADRH registers form a two-byte word that holds the 13-bit address of the EEPROM location being accessed. These devices have 1K or 2K words of program Flash, with an address range from 0000h to 03FFh for the PIC16F818 and 0000h to 07FFh for the PIC16F819. Addresses above the range of the respective device will wraparound to the beginning of program memory.

The EEPROM data memory allows single byte read and write. The Flash program memory allows singleword reads and four-word block writes. Program memory writes must first start with a 32-word block erase, then write in 4-word blocks. A byte write in data EEPROM memory automatically erases the location and writes the new data (erase before write).

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump, rated to operate over the voltage range of the device for byte or word operations.

When the device is code-protected, the CPU may continue to read and write the data EEPROM memory. Depending on the settings of the write-protect bits, the device may or may not be able to write certain blocks of the program memory; however, reads of the program memory are allowed. When code-protected, the device programmer can no longer access data or program memory; this does NOT inhibit internal reads or writes.

3.1 EEADR and EEADRH

The EEADRH:EEADR register pair can address up to a maximum of 256 bytes of data EEPROM or up to a maximum of 8K words of program EEPROM. When selecting a data address value, only the LSB of the address is written to the EEADR register. When selecting a program address value, the MSB of the address is written to the EEADRH register and the LSB is written to the EEADR register.

If the device contains less memory than the full address reach of the address register pair, the Most Significant bits of the registers are not implemented. For example, if the device has 128 bytes of data EEPROM, the Most Significant bit of EEADR is not implemented on access to data EEPROM.

3.2 EECON1 and EECON2 Registers

EECON1 is the control register for memory accesses.

Control bit, EEPGD, determines if the access will be a program or data memory access. When clear, as it is when Reset, any subsequent operations will operate on the data memory. When set, any subsequent operations will operate on the program memory.

Control bits, RD and WR, initiate read and write, respectively. These bits cannot be cleared, only set in software. They are cleared in hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write or erase operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write (or erase) operation is interrupted by a MCLR or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and rewrite the location. The data and address will be unchanged in the EEDATA and EEADR registers.

Interrupt flag bit, EEIF in the PIR2 register, is set when the write is complete. It must be cleared in software.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the EEPROM write sequence.

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

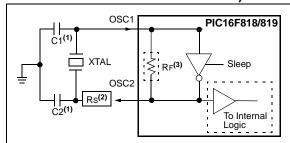
The PIC16F818/819 can be operated in eight different oscillator modes. The user can program three configuration bits (FOSC2:FOSC0) to select one of these eight modes (modes 5-8 are new PIC16 oscillator configurations):

1.	LP	Low-Power Crystal
2.	XT	Crystal/Resonator
3.	HS	High-Speed Crystal/Resonator
4.	RC	External Resistor/Capacitor with Fosc/4 output on RA6
5.	RCIO	External Resistor/Capacitor with I/O on RA6
6.	INTIO1	Internal Oscillator with Fosc/4 output on RA6 and I/O on RA7
7.	INTIO2	Internal Oscillator with I/O on RA6 and RA7
8.	ECIO	External Clock with I/O on RA6

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKI and OSC2/CLKO pins to establish oscillation (see Figure 4-1 and Figure 4-2). The PIC16F818/819 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 4-1: CRYSTAL OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 4-1 for typical values of C1 and C2.

- **2:** A series resistor (Rs) may be required for AT strip cut crystals.
- 3: RF varies with the crystal chosen (typically between 2 $M\Omega$ to 10 $M\Omega).$

TABLE 4-1: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR (FOR DESIGN GUIDANCE ONLY)

Osc Type	Crystal Freq	Typical Capacitor Value Tested:			
	rreq	C1	C2		
LP	32 kHz	33 pF	33 pF		
	200 kHz	15 pF	15 pF		
XT	200 kHz	56 pF	56 pF		
	1 MHz	15 pF	15 pF		
	4 MHz	15 pF	15 pF		
HS	4 MHz	15 pF	15 pF		
	8 MHz	15 pF	15 pF		
	20 MHz	15 pF	15 pF		

Capacitor values are for design guidance only.

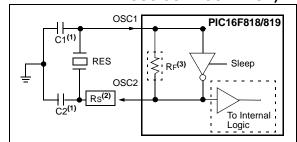
These capacitors were tested with the crystals listed below for basic start-up and operation. These values were not optimized.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following this table for additional information.

- **Note 1:** Higher capacitance increases the stability of the oscillator but also increases the start-up time.
 - 2: Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.
 - **3:** Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.
 - **4:** Always verify oscillator performance over the VDD and temperature range that is expected for the application.

FIGURE 4-2: CERAMIC RESONATOR OPERATION (HS OR XT OSC CONFIGURATION)



- Note 1: See Table 4-2 for typical values of C1 and C2.
 - 2: A series resistor (Rs) may be required.
 - 3: RF varies with the resonator chosen (typically between 2 M Ω to 10 M Ω).

TABLE 4-2: CERAMIC RESONATORS (FOR DESIGN GUIDANCE ONLY)

Typical Capacitor Values Used:							
Mode Freq OSC1 OSC2							
XT	455 kHz	56 pF	56 pF				
	2.0 MHz	47 pF	47 pF				
	4.0 MHz	33 pF	33 pF				
HS	8.0 MHz	27 pF	27 pF				
	16.0 MHz	22 pF	22 pF				

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. These values were not optimized.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following this table for additional information.

Note:

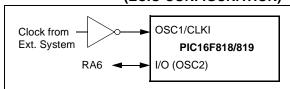
When using resonators with frequencies above 3.5 MHz, the use of HS mode rather than XT mode is recommended. HS mode may be used at any VDD for which the controller is rated. If HS is selected, it is possible that the gain of the oscillator will overdrive the resonator. Therefore, a series resistor should be placed between the OSC2 pin and the resonator. As a good starting point, the recommended value of Rs is 330Ω .

4.3 External Clock Input

The ECIO Oscillator mode requires an external clock source to be connected to the OSC1 pin. There is no oscillator start-up time required after a Power-on Reset or after an exit from Sleep mode.

In the ECIO Oscillator mode, the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 4-3 shows the pin connections for the ECIO Oscillator mode.

FIGURE 4-3: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



NOTES:

7.5 Timer1 Operation in Asynchronous Counter Mode

If control bit, T1SYNC (T1CON<2>), is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow that will wake-up the processor. However, special precautions in software are needed to read/write the timer.

In Asynchronous Counter mode, Timer1 cannot be used as a time base for capture or compare operations.

7.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. The example codes provided in Example 7-1 and Example 7-2 demonstrate how to write to and read Timer1 while it is running in Asynchronous mode.

EXAMPLE 7-1: WRITING A 16-BIT FREE RUNNING TIMER

```
; All interrupts are disabled
CLRF
        TMR1L
                  ; Clear Low byte, Ensures no rollover into TMR1H
MOVLW
        HI BYTE
                   ; Value to load into TMR1H
MOVWF
        TMR1H, F
                   ; Write High byte
        LO BYTE
MOVLW
                   ; Value to load into TMR1L
MOVWF
        TMR1H, F
                    ; Write Low byte
; Re-enable the Interrupt (if required)
CONTINUE
                    ; Continue with your code
```

EXAMPLE 7-2: READING A 16-BIT FREE RUNNING TIMER

```
; All interrupts are disabled
MOVF
        TMR1H, W ; Read high byte
MOVWF
        TMPH
MOVF
        TMR1L, W
                  ; Read low byte
MOVWF
        TMPL
        TMR1H, W
MOVF
                   ; Read high byte
        TMPH, W
                    ; Sub 1st read with 2nd read
SUBWF
       STATUS, Z; Is result = 0
BTFSC
       CONTINUE ; Good 16-bit read
; TMR1L may have rolled over between the read of the high and low bytes.
; Reading the high and low bytes now will read a good value.
MOVF
        TMR1H, W
                 ; Read high byte
MOVWF
        TMPH
                   ; Read low byte
MOVF
        TMR1L, W
MOVWF
        TMPL
                    ; Re-enable the Interrupt (if required)
CONTINUE
                    ; Continue with your code
```

9.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on the CCP1 pin. An event is defined as:

- · Every falling edge
- · Every rising edge
- · Every 4th rising edge
- · Every 16th rising edge

An event is selected by control bits, CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit, CCP1IF (PIR1<2>), is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value is overwritten by the new captured value.

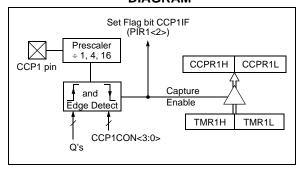
9.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCP1 pin should be configured as an input by setting the TRISB<x> bit.

Note 1: If the CCP1 pin is configured as an output, a write to the port can cause a capture condition.

2: The TRISB bit (2 or 3) is dependent upon the setting of configuration bit 12 (CCPMX).

FIGURE 9-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



9.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

9.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit, CCP1IE (PIE1<2>), clear to avoid false interrupts and should clear the flag bit, CCP1IF, following any such change in operating mode.

9.1.4 CCP PRESCALER

There are four prescaler settings specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared; therefore, the first capture may be from a non-zero prescaler. Example 9-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 9-1: CHANGING BETWEEN CAPTURE PRESCALERS

	CCP1CON NEW_CAPT_PS	;Turn CCP module off ;Load the W reg with
MOVWF	CCP1CON	;the new prescaler ;move value and CCP ON ;Load CCP1CON with this ;value

10.3 SSP I²C Mode Operation

The SSP module in I²C mode fully implements all slave functions, except general call support and provides interrupts on Start and Stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications, as well as 7-bit and 10-bit addressing.

Two pins are used for data transfer. These are the RB4/SCK/SCL pin, which is the clock (SCL) and the RB1/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISB<4,1> bits.

To ensure proper communication of the I^2C Slave mode, the TRIS bits (TRISx [SDA, SCL]) corresponding to the I^2C pins must be set to '1'. If any TRIS bits (TRISx<7:0>) of the port containing the I^2C pins (PORTx [SDA, SCL]) are changed in software during I^2C communication using a Read-Modify-Write instruction (BSF, BCF), then the I^2C mode may stop functioning properly and I^2C communication may suspend. Do not change any of the TRISx bits (TRIS bits of the port containing the I^2C pins) using the instruction BSF or BCF during I^2C communication. If it is absolutely necessary to change the TRISx bits during communication, the following method can be used:

EXAMPLE 10-1:

```
MOVF TRISC, W ; Example for an 18-pin part such as the PIC16F818/819

IORLW 0x18 ; Ensures <4:3> bits are '11'

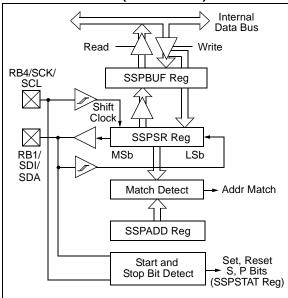
ANDLW B'11111001' ; Sets <2:1> as output, but will not alter other bits

; User can use their own logic here, such as IORLW, XORLW and ANDLW

MOVWF TRISC
```

The SSP module functions are enabled by setting SSP Enable bit, SSPEN (SSPCON<5>).

FIGURE 10-5: SSP BLOCK DIAGRAM (I²C™ MODE)



The SSP module has five registers for I²C operation:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address) with Start and Stop bit interrupts enabled to support Firmware Master mode
- I²C Slave mode (10-bit address) with Start and Stop bit interrupts enabled to support Firmware Master mode
- I²C Firmware Controlled Master mode with Start and Stop bit interrupts enabled, slave is Idle

Selection of any I²C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open-drain, provided these pins are programmed to inputs by setting the appropriate TRISB bits. Pull-up resistors must be provided externally to the SCL and SDA pins for proper operation of the I²C module.

Additional information on SSP I²C operation may be found in the "PIC® Mid-Range MCU Family Reference Manual" (DS33023).

The ADRESH:ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the A/D Result register pair, the GO/DONE bit (ADCON0<2>) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 11-1.

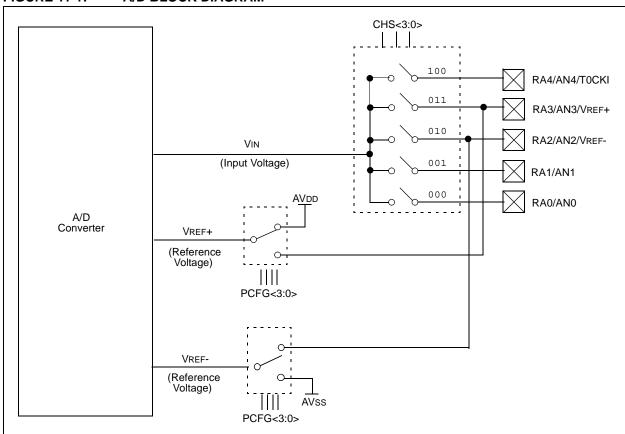
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs.

To determine sample time, see **Section 11.1 "A/D Acquisition Requirements"**. After this sample time has elapsed, the A/D conversion can be started.

These steps should be followed for doing an A/D conversion:

- 1. Configure the A/D module:
 - Configure analog pins/voltage reference and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)
- 2. Configure A/D interrupt (if desired):
 - · Clear ADIF bit
 - · Set ADIE bit
 - · Set GIE bit
- 3. Wait the required acquisition time.
- 4. Start conversion:
 - Set GO/DONE bit (ADCON0)
- 5. Wait for A/D conversion to complete by either:
 - Polling for the GO/DONE bit to be cleared (with interrupts disabled); OR
 - Waiting for the A/D interrupt
- Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF if required.
- 7. For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 11-1: A/D BLOCK DIAGRAM



11.4 A/D Conversions

Clearing the GO/DONE bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. That is, the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers). After the A/D conversion is aborted, a 2-TAD wait is required before the next acquisition is started. After this 2-TAD wait, acquisition on the selected channel is automatically started. The GO/DONE bit can then be set to start the conversion.

In Figure 11-3, after the GO bit is set, the first time segment has a minimum of TCY and a maximum of TAD.

Note: The GO/DONE bit should NOT be set in the same instruction that turns on the A/D.

11.4.1 A/D RESULT REGISTERS

The ADRESH:ADRESL register pair is the location where the 10-bit A/D result is loaded at the completion of the A/D conversion. This register pair is 16 bits wide. The A/D module gives the flexibility to left or right justify the 10-bit result in the 16-bit result register. The A/D Format Select bit (ADFM) controls this justification. Figure 11-4 shows the operation of the A/D result justification. The extra bits are loaded with '0's. When an A/D result will not overwrite these locations (A/D disable), these registers may be used as two general purpose 8-bit registers.

FIGURE 11-3: A/D CONVERSION TAD CYCLES

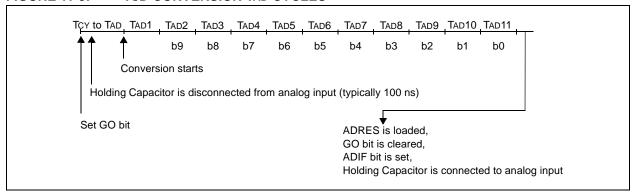
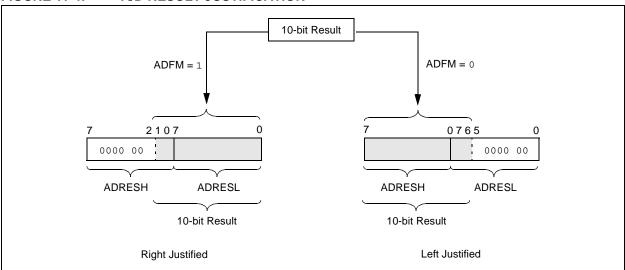


FIGURE 11-4: A/D RESULT JUSTIFICATION



NOTES:

TABLE 13-2: PIC16F818/819 INSTRUCTION SET

Mnemor	nic,	Description	Cycles		14-Bit	Opcode	9	Status	Natas
Operan	ds	Description		MSb			LSb	Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C, DC, Z	1, 2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1, 2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1, 2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1, 2
DECFSZ	f, d	Decrement f, Skip if 0	1 (2)	00	1011	dfff	ffff		1, 2, 3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1, 2
INCFSZ	f, d	Increment f, Skip if 0	1 (2)	00	1111	dfff	ffff		1, 2, 3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1, 2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1, 2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1, 2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1, 2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C, DC, Z	1, 2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1, 2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1, 2
		BIT-ORIENTED FILE REGIST	ER OPER	RATION	NS				
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1, 2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1, 2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
		LITERAL AND CONTROL	OPERAT	IONS					
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C, DC, Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO, PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into Standby mode	1	00	0000	0110	0011	TO, PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

Note: Additional information on the mid-range instruction set is available in the "PIC® Mid-Range MCU Family Reference Manual" (DS33023).

^{2:} If this instruction is executed on the TMR0 register (and where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 module.

^{3:} If the Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

14.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

14.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC[®] Flash MCUs and dsPIC[®] Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with incircuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

14.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

14.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC[®] and dsPIC[®] Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming[™].

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

15.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias	40°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD and $\overline{\text{MCLR}}$)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	0.3 to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0.3 to +14V
Total power dissipation (Note 1)	1W
Maximum current out of Vss pin	200 mA
Maximum current into VDD pin	
Input clamp current, lik (VI < 0 or VI > VDD)	±20 mA
Output clamp current, lok (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA	100 mA
Maximum current sourced by PORTA	100 mA
Maximum current sunk by PORTB	100 mA
Maximum current sourced by PORTB	100 mA
Note 1: Power dissipation is calculated as follows: Pdis = $VDD \times \{IDD - \sum IOH\} + \sum \{(VD - \sum IOH)\} + \sum \{($	$D = VOH(x IOH) + \Sigma(VO(x IO))$

Note 1: Power dissipation is calculated as follows: Pdis = VDD $x \{IDD - \sum IOH\} + \sum \{(VDD - VOH) \times IOH\} + \sum \{(VDL \times IOL) \times IOH\} + \sum \{(VDL \times IOH) \times$

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

^{2:} Voltage spikes at the MCLR pin may cause latch-up. A series resistor of greater than 1 kΩ should be used to pull MCLR to VDD, rather than tying the pin directly to VDD.

FIGURE 15-10: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

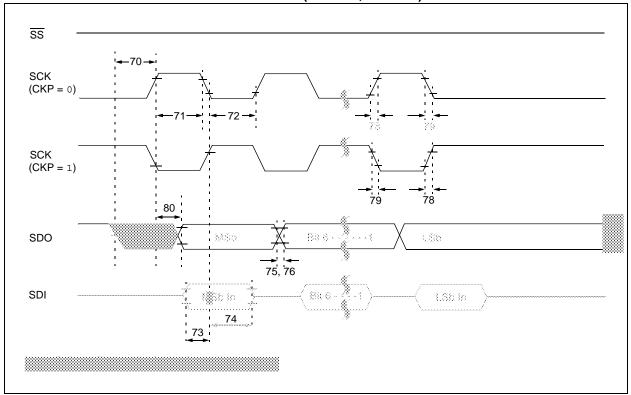


FIGURE 15-11: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)

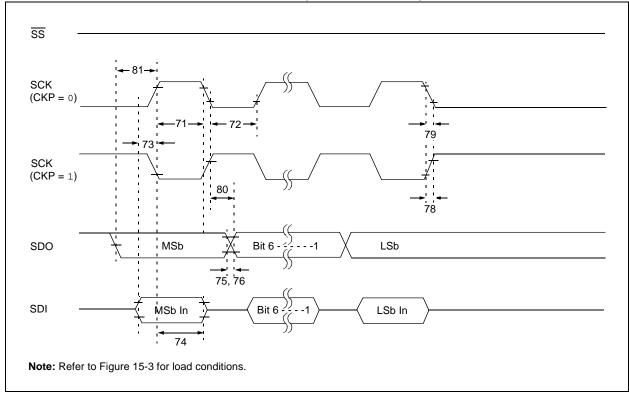


FIGURE 16-19: TYPICAL, MINIMUM AND MAXIMUM Vol vs. Iol (VDD = 5V, -40°C TO +125°C)

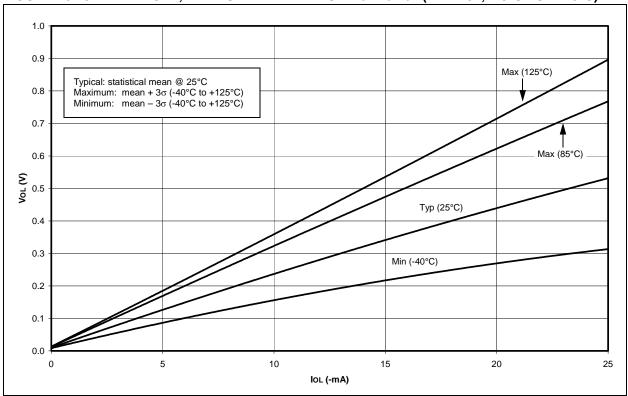
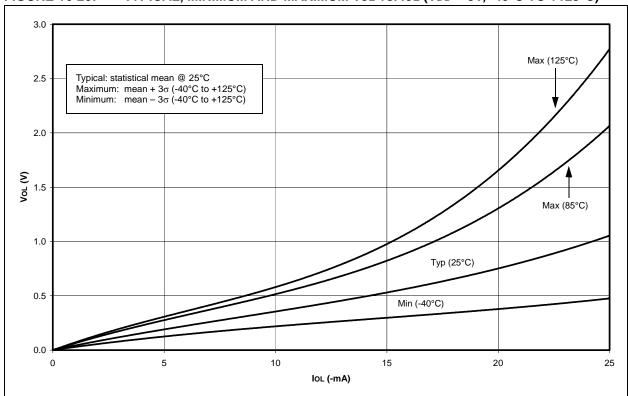
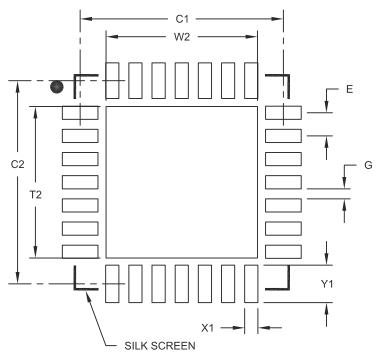


FIGURE 16-20: TYPICAL, MINIMUM AND MAXIMUM Vol vs. Iol (VDD = 3V, -40°C TO +125°C)



28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

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